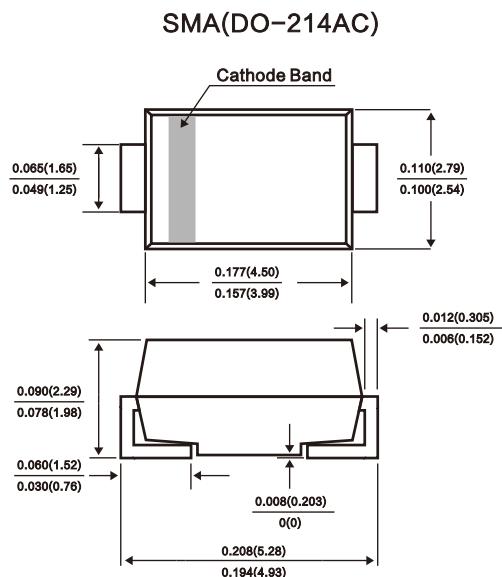


FEATURES

- For surface mounted applications in order to optimize board space
- Glass passivated junction
- Built-in strain relief
- Excellent clamping capability
- Low profile package
- Low inductance
- Excellent clamping capability
- Fast response time: typically less than 1.0 ps from 0 volts to BV min
- Typical IR less than 1 μ A above 10V
- High temperature soldering guaranteed: 250°C/10 seconds at terminals

**MECHANICAL DATA**

Dimensions in inches and (millimeters)

Case: JEDEC DO-214AC Molded plastic

Terminal : Solder plated, solderable per

MIL-STD-750, Method 2026

Polarity: Color band denoted positive end (cathode)

except Bipolar

Standard Packaging: 12mm tape(EIA STD RS-481)

Weight: 0.002 ounces, 0.061 grams

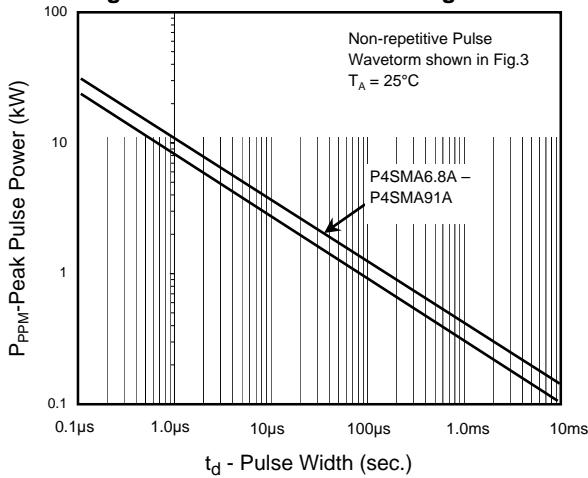
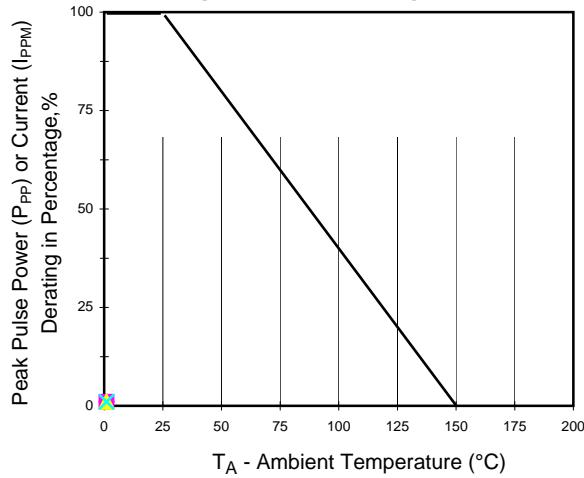
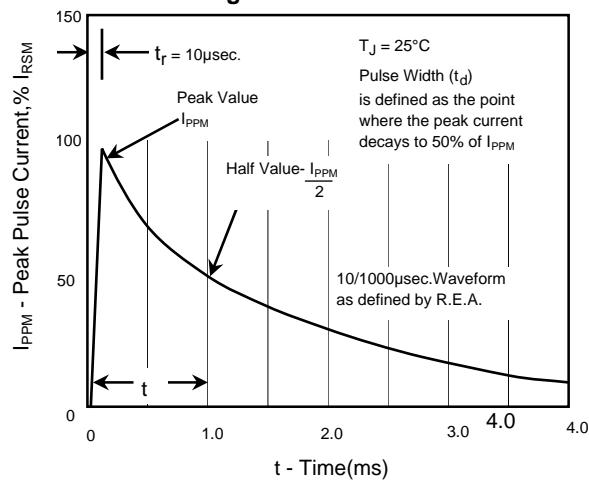
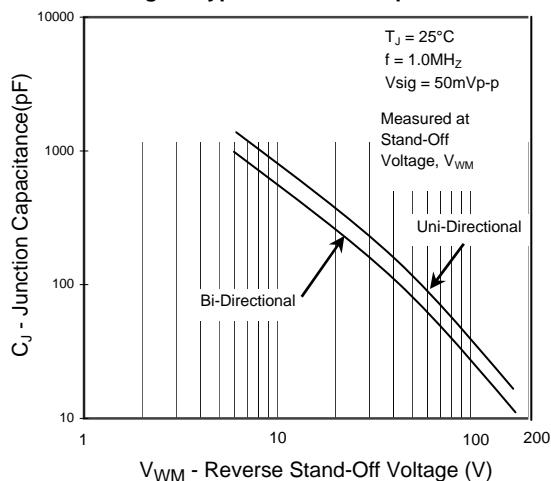
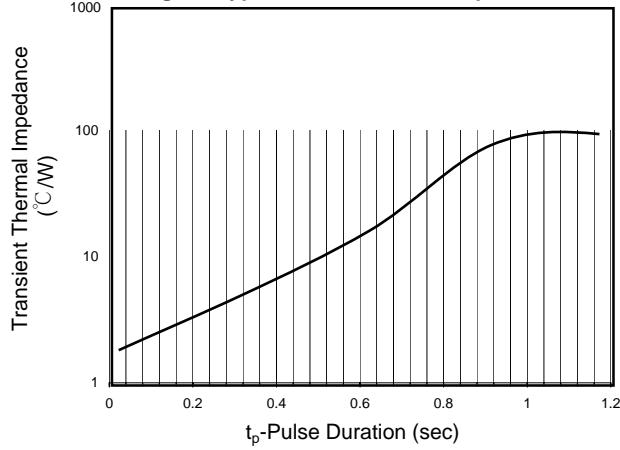
MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

RATING	SYMBOL	VALUE	UNITS
Peak Pulse Power Dissipation at TA = 25 °C, TP = 1ms (Note 1)	P _{PPM}	Minimum 400	Watts
Maximum Instantaneous Forward Voltage at 25.0A for Unidirectional Only	V _F	3.5	Volts
Steady State Power Dissipation at TL = 75°C Lead lengths .375", 9.5mm (Note 2)	P _{M(AV)}	1.0	Watts
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load, (JEDEC Method)(Note 3)	I _{FSM}	40	Amps
Operatings and Storage Temperature Range	T _J , T _{STG}	-55 +150	°C

NOTES:

1. Non-repetitive current pulse, per Fig.3 and derated above Ta=25 °C per Fig.2.
2. Mounted on 5.0mm² (0.03mm thick) Copper Pads to each termina
3. 8.3ms single half sine-wave, or equivalent square wave, Duty cycle=4 pulses per minutes maximum.

Fig. 1 - Peak Pulse Power Rating Curve**Fig.2 - Pulse Derating Curve****Fig.3 - Pulse Waveform****Fig.4 - Typical Junction Capacitance****Fig. 5 - Typ. Transient Thermal Impedance****Fig.6 - Maximum Non-Repetitive Peak Forward Surge Current Uni-Directional Only**